

A

B

C

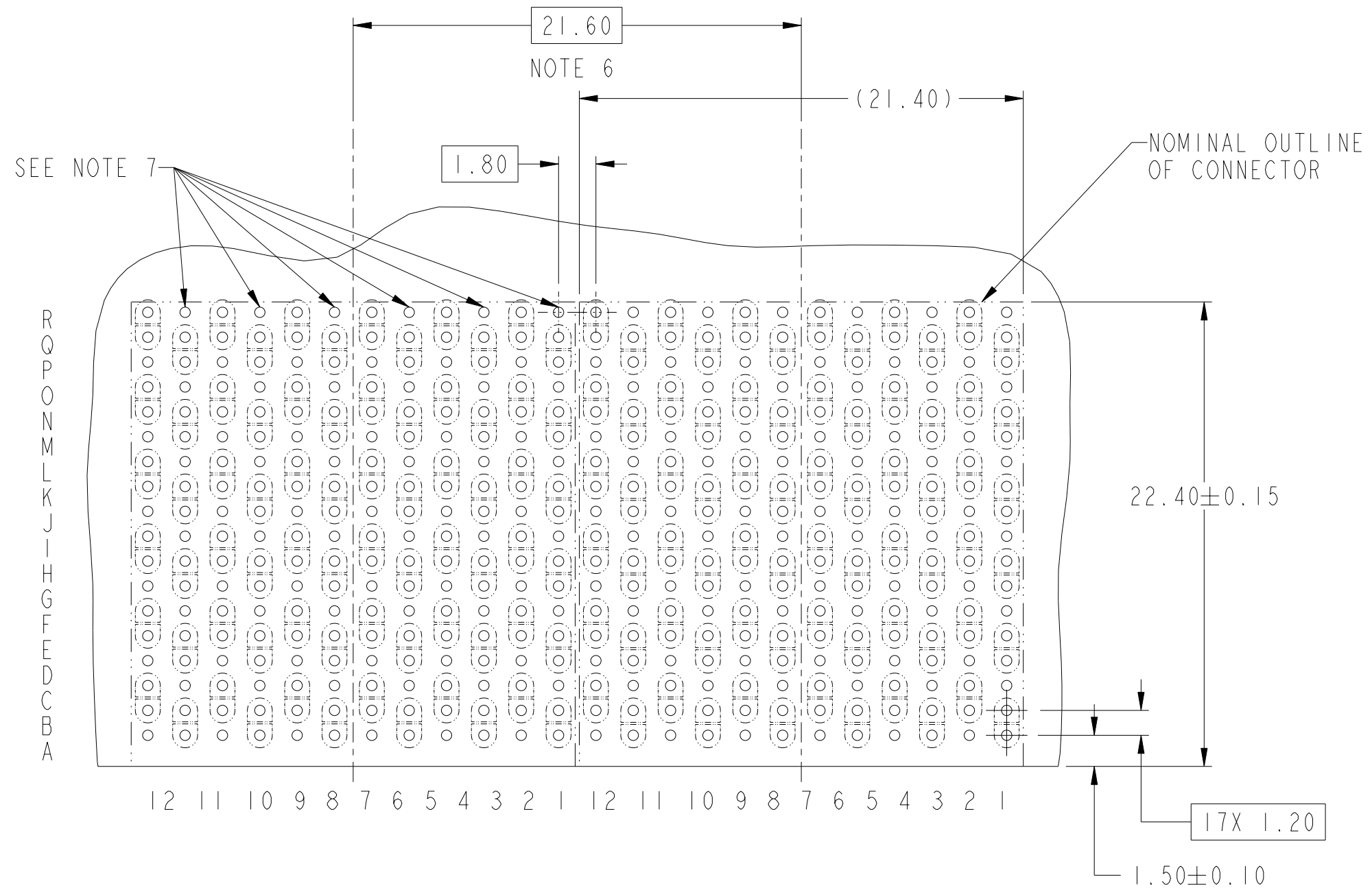
D

A

B

C

D



RECOMMENDED PCB LAYOUT
FOR DIFFERENTIAL APPLICATIONS
COMPONENT SIDE
(TWO ADJACENT FOOTPRINTS SHOWN)
NOTES 6, 7, & 8



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	title		ZipLine R/A REC ASSY		dwg no	10076209		Rev.	A
			6 PR, 12 IMLA, 1.8MM PITCH, 21.6MM						
	catalog no		-		CUSTOMER		sheet 2 of 3		

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PRODUCT NUMBER	PLATING TYPE
10076209-101	TIN/LEAD ALLOY OVER NICKEL
10076209-101LF	TIN OVER NICKEL (LEAD FREE)

A

B

C

D

- ① - CONNECTOR MATERIALS:
HOUSING: HIGH TEMP THERMOPLASTIC, BLACK, UL94-V0
IMLA PLASTIC: HIGH TEMP THERMOPLASTIC, BLACK, UL94-V0
CONTACT: COPPER ALLOY
ORGANIZER: STAINLESS STEEL
- 2 - CONTACT PLATING:
SEPARABLE INTERFACE:
PERFORMANCE-BASED PLATING, QUALIFIED TO MEET THE
REQUIREMENTS OF FCI PRODUCT SPECIFICATION GS-12-452
INCLUDING TELCORDIA GR-1217-CORE (NOVEMBER 1995)
CENTRAL OFFICE TEST SEQUENCE
- PRESS-FIT TAILS: SEE TABLE
- 3 - PRODUCT SPECIFICATION: GS-12-452
- 4 - APPLICATION SPECIFICATION: GS-20-094
- ⑤ - PRODUCT MARKING, (PART NUMBER & LOT CODE), ON THIS SURFACE.
- ⑥ - THE MINIMUM CENTERLINE SPACING BETWEEN ADJACENT
MODULES IS 21.6MM.
- ⑦ - THERE IS NO GROUND BUSSING WITHIN THE CONNECTOR EXCEPT FOR
POSITIONS R1,R3,R5,R7,R9,& R11. THESE MUST BE ASSIGNED AS GROUNDS.

- ⑧ - REFER TO CUSTOMER DRAWING 10045979 FOR INFORMATION
ON PCB HOLE DIAMETERS AND PLATING OPTIONS
- 9 - LEAD FREE PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES &
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 10 - THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION,
INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
- 11 - PACKAGING MEETS GS-14-920 LEAD FREE LABELING
SPECIFICATION.

A

B

C

D



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			6 PR, 12 IMLA, 1.8MM PITCH, 21.6MM					A
	catalog no		-		CUSTOMER		sheet 3 of 3	

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